

In The United States Patent And Trademark Office

Applicants

Billiet et al.

Application No.

10/082,867

Filed

February 18, 2002

Title

Ultrasmall semiconductor bonding tools and method of fabrication

thereof.

Penang, Malaysia, Friday, June 10, 2005

Petition to Make Special

Honorable Commissioner for Patents PO Box 1450 Alexandria, Virginia 22313-1450, USA

Sir:

Applicants hereby respectfully petition that the above application be made special under MPEP §708.02 for the following reason:

- Manufacturer Available
- Infringement Exists
- iii. a Applicant's Health is Poor
- iv. Applicant's Age is 65 or Greater
- v. a Environmental Quality Will Be Enhanced
- vi. o Energy Savings Will Result

- vii.

 Recombinant DNA is involved
- viii. o Special Procedure Search Was Made
- Relates to HIV/AIDS or Cancer
- xi. D Counters Terrorism

A copy of a Certificate of Residence issued by the Embassy of Belgium in Kuala Lumpur and stating applicant's date of birth (June 27, 1938) is attached in support of this petition.

Very respectfully submitted,

Romain L. Billiet

Applicants Pro Se

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Certificate of Mailing: I certify that on the date below this document will be deposited with the Malaysian Postal Services as Express Airmail in an envelope addressed to: COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450, USA

June 10, 2005

Romain L. Billiet, Applicant

GRANTED

Richard Crispino Special Program Examiner

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